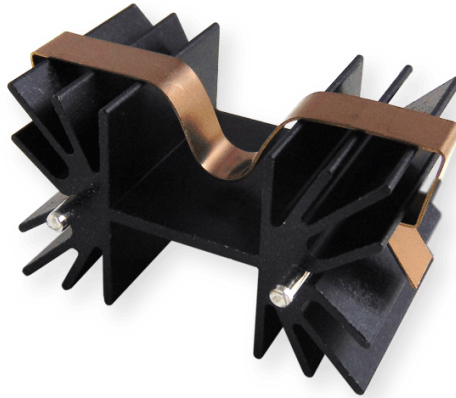


Product features PR

33/25,4/MC

Semiconductor casing:	TO-220 ; TO-218 ; TOP-3
Semiconductor mounted by:	Clip Mounting
Heat sink mounted by:	Solder
Finish	Black Anodised
Material	AlMgSi0,5
Width [mm]:	42.0
Height [mm]:	25.0
Length [mm]:	25.4
Min. thermal resistance [K/ W]:	6.0



Further information

- Special extruded heatsink for semiconductor case TO220, TO218(TOP3) - Aluminium, anodised black, solderable - Standard heights: 25.4, 38.1, 50.8 and 63.5 mm - Version MC (Mounting clip) for clip mounting of semiconductor. - Heatsink solderable by tin plated solder pins

